L Number	Hits	Search Text	DB	Time stamp
1	0	20020153532.pn. and molten	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 16:56
3	280	(ceramic adj substrate) with molten	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 16:56
4	1	(ceramic adj substrate) with molten with (base adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:36
5	47	(ceramic adj substrate) with (molten adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:28
6	90	(ceramic adj substrate) same (molten adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:26
7	7	(ceramic adj substrate) same (melted adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:26
8	51	(ceramic adj plate) with (molten adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:28
9	0	(ceramic adj plate) with molten with (base adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:37
10	0	(ceramic adj plate) same molten same (base adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:39
11	0	(upper adj circuit adj plate) same molten same (base adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:40
12	0	(upper adj circuit adj plate) same (base adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:40
13	0	(upper adj circuit adj plate) and (base adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:40
14	3	(upper adj circuit adj plate) and (molten adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:41
15	408	(upper adj plate) and (molten adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:47

16	141	(upper adj plate) same (molten adj metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:41
17	3	(upper adj plate) same (molten adj metal)same ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:42
18	3	(upper adj plate) same (molten adj metal) same ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:42
19	101	(upper adj plate) and (molten adj metal) and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:42
20	1	(upper adj plate) and (molten adj metal) and (power adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:30
21	27	257/150.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:31
22	160	257/177.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:31
23	30	257/180.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:31
24	53	257/182.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:32
25	1564	257/686.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:33
26	528	257/684.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:34
27	488	257/685.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:34
28	702	257/687.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:35
29	672	257/703.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:38

30	483	257/705.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:40
31	1167	257/706.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:42
32	2185	257/712.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:44
33	1141	257/713.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:47
34	960	257/717.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:48
35	2865	257/758.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:53
36	1159	257/750.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:57
37	940	257/762.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:58
38	419	257/765.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 18:59
39	418	257/772.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 19:00
-	33	(power adj semiconductor adj module) and (heat adj sink) and (ceramic adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 11:13
-	4	(power adj semiconductor adj module) and (casting adj method)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 14:44
-	13	(casting adj method) and (heat adj sink) and (ceramic adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:17
-	20	(chip) and (circuit adj plate) and (heat adj sink) and (ceramic adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:17

-	0	(power adj semiconductor adj module) and (integrally adj formed adj terminals)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 17:05
-	1	(power adj semiconductor adj module) and (integral adj terminals)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 17:07
-	8	(outer adj case) and (integral adj terminals)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 17:07
-	24	no adj lower adj plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 11:16
-	52	(circuit adj plate) and (power adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 11:58
-	7	(circuit adj plate) and (casting adj method)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 11:40
-	5	(circuit adj plate) and (packaging adj method)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 11:40
-	43	power adj module adj package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 12:22
-	591	(power adj module) with case	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 12:23
-	19	(power adj module) with case with ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 12:23
-	11	solder adj material adj removed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:32
-	17	solder adj layer adj removed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 11:41
-	22	no adj solder adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 11:56
-	0	no adj solder adj film	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:31

-	1	no adj solder adj region	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:05
-	120	(metal adj base) with (ceramic adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:10
-	24	((metal adj base) with (ceramic adj substrate)) and (power adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 14:25
-	3	no adj solder adj join	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:31
-	4	solder adj material adj omitted	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:32
-	3	solder adj layer adj omitted	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:32
-	3	(base adj integral adj type) and (power adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 16:55